ABSTRACT

A peeling device peels a bonded substrate formed by bonding a first substrate and a second substrate. In a holding jig including a dicing frame having an opening and dicing tape fixed to the dicing frame to close the opening, the bonded substrate is pasted on the dicing tape by being disposed in the opening. The peeling device includes a holding part configured to hold the bonded substrate by suctioning the dicing tape of the holding jig. The holding part includes a center region and an outer peripheral region partitioned from the center region and looping around the center region on an outer side of the center region, and is configured to apply a suctioning pressure for suctioning the dicing tape via each of the center region and the outer peripheral region.

Fig. 8